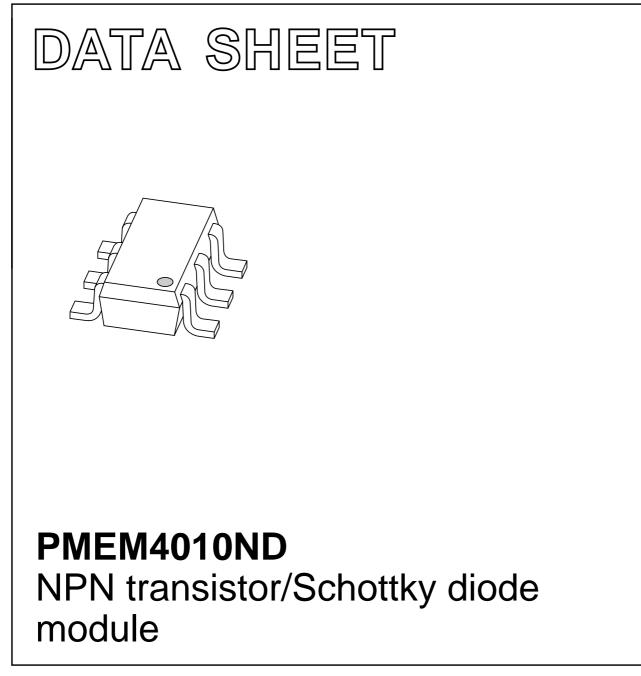
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2002 Oct 28 2003 Jul 04



### FEATURES

- 600 mW total power dissipation
- High current capability
- Reduces required PCB area
- Reduced pick and place costs
- Small plastic SMD package.

### Transistor:

• Low collector-emitter saturation voltage.

### Diode:

- Ultra high-speed switching
- Very low forward voltage
- Guard ring protected.

### APPLICATIONS

- DC/DC convertors
- Inductive load drivers
- General purpose load drivers
- Reverse polarity protection circuits.

### DESCRIPTION

Combination of an NPN transistor with low  $V_{CEsat}$  and high current capability and a planar Schottky barrier diode with an integrated guard ring for stress protection in a SOT457 (SC-74) small plastic package.

PNP complement: PMEM4010PD.

### PINNING

PIN	DESCRIPTION	
1	emitter	
2	not connected	
3	cathode	
4	anode	
5	base	
6	collector	

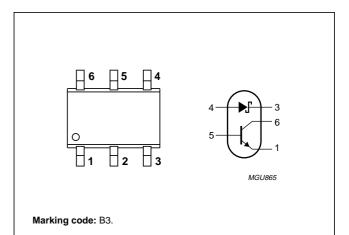


Fig.1 Simplified outline (SOT457) and symbol.

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### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
NPN trans	istor				
V <sub>CBO</sub>	collector-base voltage	open emitter	-	40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	40	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	5	V
I <sub>C</sub>	collector current (DC)		-	1	A
I <sub>CM</sub>	peak collector current		-	2	A
I <sub>BM</sub>	peak base current		-	1	A
Tj	junction temperature		-	150	°C
Schottky b	barrier diode	•	·	•	
V <sub>R</sub>	continuous reverse voltage		_	20	V
I <sub>F</sub>	continuous forward current		-	1	A
I <sub>FSM</sub>	non repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method	-	5	A
Tj	junction temperature		_	125	°C
Combined	l device	•			
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	600	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>amb</sub>	operating ambient temperature	note 2	-65	+125	°C

#### Notes

1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses P<sub>R</sub> are significant part of the total power losses. Nomograms for determination of the reverse power losses P<sub>R</sub> and I<sub>F</sub> (AV) rating will be available on request.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air; note 1	208	K/W	

#### Note

1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

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### ELECTRICAL CHARACTERISTICS

### $T_{amb}$ = 25 $^\circ C$ unless otherwise specified.

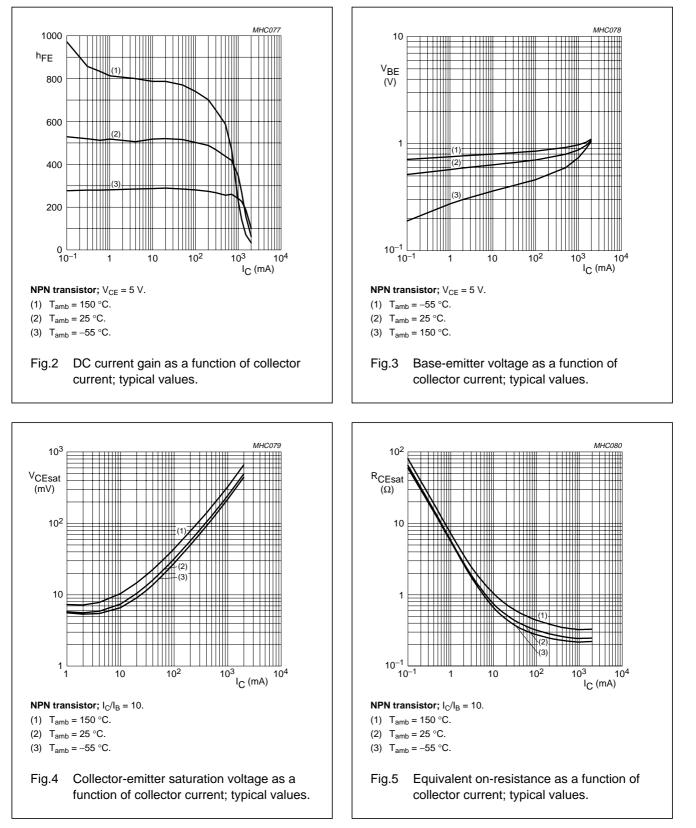
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
NPN trans	sistor		!	1	!	4
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = 40 \text{ V}; I_E = 0$	-	-	100	nA
		$V_{CB} = 40 \text{ V}; \text{ I}_{E} = 0; \text{ T}_{amb} = 150 ^{\circ}\text{C}$	_	-	50	μA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}; I_B = 0$	_	-	100	nA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 V; I_{C} = 0$	-	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 mA	300	-	_	
		$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 500 \text{ mA}$	300	-	900	
		V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 A	200	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 1 mA	_	-	80	mV
		I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA	_	-	110	mV
		I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	_	-	210	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	_	-	1.2	V
R <sub>CEsat</sub>	equivalent on-resistance	I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA; note 1	_	260	<220	mΩ
V <sub>BEon</sub>	base-emitter turn-on voltage	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 A	-	-	1.1	V
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 50 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	150	-	-	MHz
Cc	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	_	-	10	pF
Schottky	barrier diode					
V <sub>F</sub>	continuous forward voltage	I <sub>F</sub> = 10 mA; note 1	_	240	270	mV
		I <sub>F</sub> = 100 mA; note 1	-	300	350	mV
		I <sub>F</sub> = 1000 mA; see Fig.7; note 1	-	480	550	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 5 V; note 1	_	5	10	μA
		V <sub>R</sub> = 8 V; note 1	-	7	20	μA
		V <sub>R</sub> = 15 V; see Fig.8; note 1	-	10	50	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 5 V; f = 1 MHz; see Fig.9	-	19	25	pF

#### Note

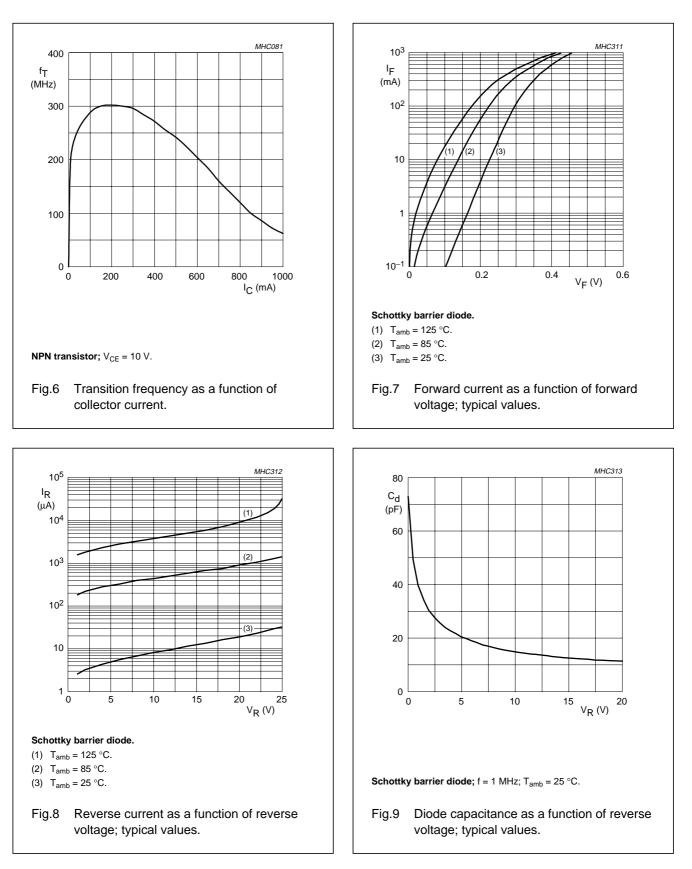
1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$ 

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### **GRAPHICAL DATA**

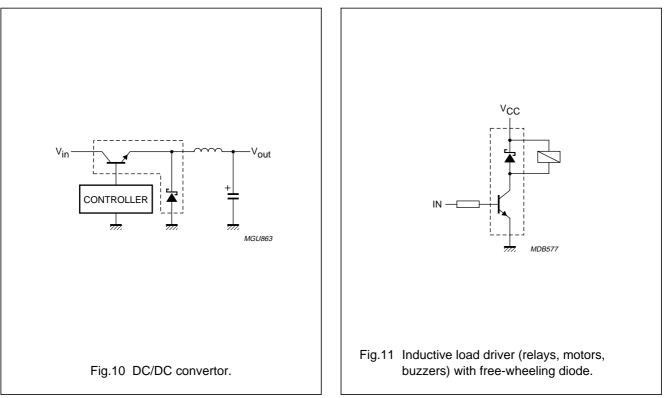


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### **APPLICATION INFORMATION**

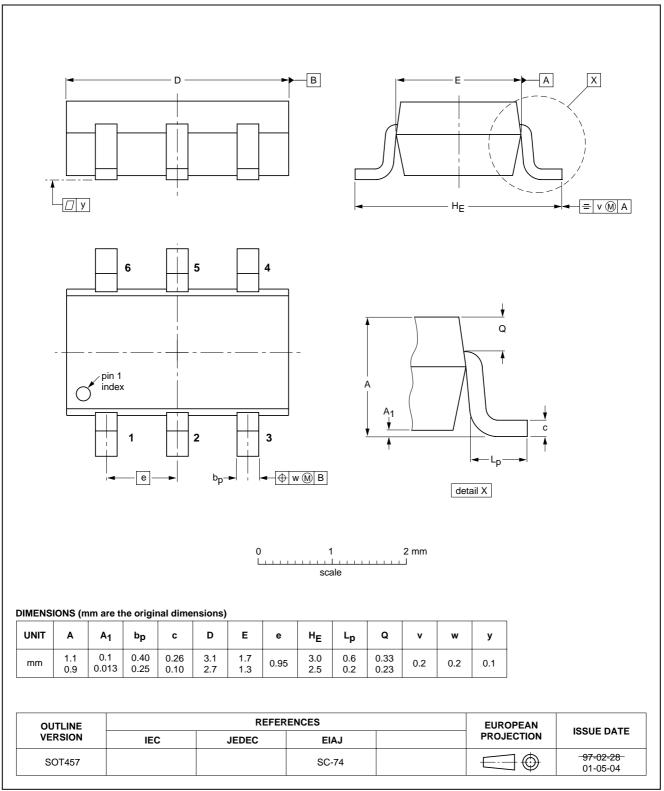


PMEM4010ND

## NPN transistor/Schottky diode module

### PACKAGE OUTLINE

### Plastic surface mounted package; 6 leads



### PMEM4010ND

### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Printed in The Netherlands

613514/02/pp10

Date of release: 2003 Jul 04

Document order number: 9397 750 11317

SCA75

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